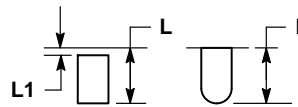
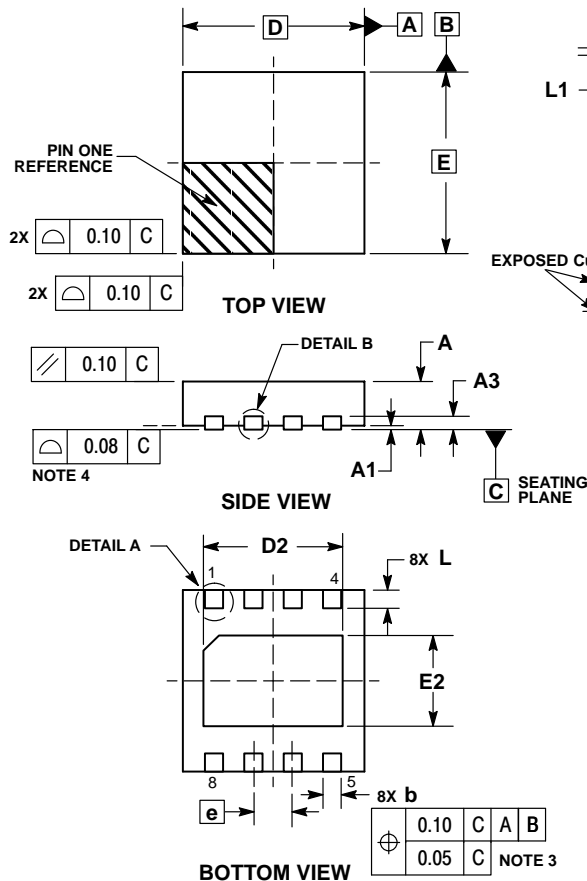
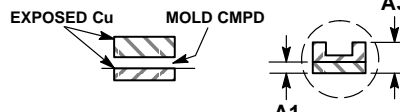




SCALE 2:1

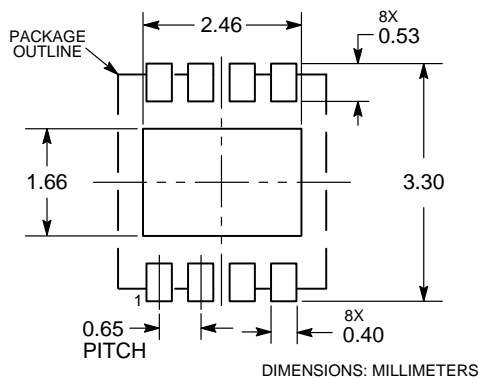
WDFN8 3x3, 0.65P
CASE 511BH
ISSUE O

DATE 21 JUL 2010


DETAIL A
ALTERNATE
CONSTRUCTIONS

DETAIL B
ALTERNATE
CONSTRUCTIONS
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.70	0.80
A1	0.00	0.05
A3	0.20	REF
b	0.25	0.35
D	3.00	BSC
D2	2.20	2.40
E	3.00	BSC
E2	1.40	1.60
e	0.65	BSC
K	0.45	REF
L	0.20	0.40
L1	---	0.15

RECOMMENDED
SOLDERING FOOTPRINT*


*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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